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| Inputs Are TTL-Voltage Compatible Center-Pin V_{CC} and GND Configurations to | D, DB, N, OR PW PACKAGE (TOP VIEW) |
|--|---------------------------------------|
| Minimize High-Speed Switching Noise | |
| EPIC [™] (Enhanced-Performance Implanted | 1Y [2 15] 2A |
| CMOS) 1-µm Process | 2Y 🚺 _{3 14} 🗍 2B |
| 500-mA Typical Latch-Up Immunity at 125°C | GND [4 13] V _{CC} |
| Package Options Include Plastic | GND [] 5 12 [] V _{CC} |
| Small-Outline Packages (D), Plastic Shrink | 3Y 🛛 6 🛛 11 🗋 3A |
| Small-Outline Packages (DB), Plastic Thin | 4Y 🛛 7 🛛 10 🗍 3B |
| Shrink Small-Outline Packages (PW), and | 4B 🛛 8 9 🗍 4A |
| Standard Plastic 300-mil DIPs (N) | |

description

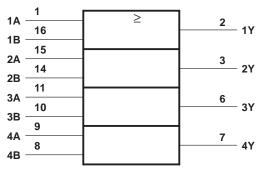
This device contains four independent 2-input OR gates. It performs the Boolean function Y = A + B or $Y = \overline{A \cdot B}$ in positive logic.

The 74ACT11032 is characterized for operation from -40°C to 85°C.

| | () | | | | | | | | | | |
|-----|-----|--------|--|--|--|--|--|--|--|--|--|
| INP | JTS | OUTPUT | | | | | | | | | |
| Α | В | Y | | | | | | | | | |
| Н | Х | Н | | | | | | | | | |
| Х | Н | н | | | | | | | | | |
| L | L | L | | | | | | | | | |

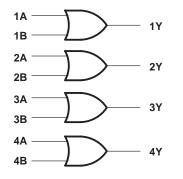
FUNCTION TABLE (each gate)

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) | |
|--|---------------------|
| Output voltage range, V _O (see Note 1) | 00 |
| Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) | ±20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ±50 mA |
| Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$ | ±50 mA |
| Continuous current through V _{CC} or GND | ±100 mA |
| Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2 | 2): D package 1.3 W |
| | DB package 0.55 W |
| | N package 1.1 W |
| | PW package 0.5 W |
| Storage temperature range, T _{stg} | · · · · · |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

| | | MIN | MAX | UNIT |
|---------------------|------------------------------------|-----|-----|------|
| VCC | Supply voltage | 4.5 | 5.5 | V |
| VIH | High-level input voltage | 2 | | V |
| VIL | Low-level input voltage | | 0.8 | V |
| VI | Input voltage | 0 | VCC | V |
| Vo | Output voltage | 0 | VCC | V |
| ЮН | High-level output current | | -24 | mA |
| IOL | Low-level output current | | 24 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | 0 | 10 | ns/V |
| ТА | Operating free-air temperature | -40 | 85 | °C |



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| DADAMETER | | V | Тŗ | Δ = 25°C | ; | MINI | | UNIT |
|----------------------------|---|-------|------|----------|------|------|------|------|
| PARAMETER | TEST CONDITIONS | Vcc | MIN | TYP | MAX | MIN | MAX | UNIT |
| | 1011 - 50 114 | 4.5 V | 4.4 | | | 4.4 | | |
| | I _{OH} = -50 μA | 5.5 V | 5.4 | | | 5.4 | | V |
| VOH | 1011 - 24 mA | 4.5 V | 3.94 | | | 3.8 | | |
| | $I_{OH} = -24 \text{ mA}$ | | 4.94 | | | 4.8 | | |
| | $I_{OH} = -75 \text{ mA}^{\dagger}$ | 5.5 V | | | | 3.85 | | |
| | I _{OL} = 50 μA | | | | 0.1 | | 0.1 | |
| | | | | | 0.1 | | 0.1 | |
| VOL | $l_{\rm ev} = 24 {\rm m}$ | 4.5 V | | | 0.36 | | 0.44 | V |
| | I _{OL} = 24 mA | 5.5 V | | | 0.36 | | 0.44 | |
| | $I_{OL} = 75 \text{ mA}^{\dagger}$ | 5.5 V | | | | | 1.65 | |
| l | $V_{I} = V_{CC}$ or GND | 5.5 V | | | ±0.1 | | ±1 | μA |
| Icc | $V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$ | 5.5 V | | | 4 | | 40 | μΑ |
| ΔI_{CC}^{\ddagger} | One input at 3.4 V, Other inputs at GND or V_{CC} | 5.5 V | | | 0.9 | | 1 | mA |
| Ci | $V_{I} = V_{CC}$ or GND | 5 V | | 3.5 | | | | pF |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡]This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended ranges of supply voltage and free-air temperature (unless otherwise noted) (see Figure 1)

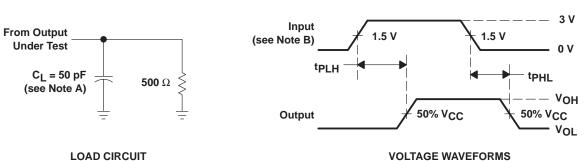
| PARAMETER | FROM | то | Т | ₄ = 25°C | ; | MIN | МАХ | UNIT |
|------------------|---------|----------|-----|----------|-----|-----|-----|------|
| PARAMETER | (INPUT) | (OUTPUT) | MIN | TYP | MAX | | | UNIT |
| ^t PLH | A or B | V | 1.5 | 6.2 | 8.1 | 1.5 | 9 | |
| ^t PHL | AUID | ř | 1.5 | 4.9 | 7.4 | 1.5 | 8 | ns |

operating characteristics, V_{CC} = 5 V, T_A = 25°C

| | PARAMETER | TEST CON | TYP | UNIT | |
|-----------------|--|-------------------------|-----------|------|----|
| C _{pd} | Power dissipation capacitance per gate | C _L = 50 pF, | f = 1 MHz | 29 | pF |



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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. CL includes probe and jig capacitance.
 - B. Input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 3 ns, t_f = 3 ns.
 - C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

| Orderable part number | Status | Material type | Package Pins | Package qty Carrier | RoHS | Lead finish/ | MSL rating/ | Op temp (°C) | Part marking |
|-----------------------|----------|---------------|----------------|-----------------------|------|---------------|--------------------|--------------|--------------|
| | (1) | (2) | | | (3) | Ball material | Peak reflow | | (6) |
| | | | | | | (4) | (5) | | |
| 74ACT11032D | Obsolete | Production | SOIC (D) 16 | - | - | Call TI | Call TI | -40 to 85 | ACT11032 |
| 74ACT11032DR | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11032 |
| 74ACT11032DR.A | Active | Production | SOIC (D) 16 | 2500 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11032 |
| 74ACT11032N | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -40 to 85 | 74ACT11032N |
| 74ACT11032N.A | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -40 to 85 | 74ACT11032N |
| 74ACT11032NE4 | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | -40 to 85 | 74ACT11032N |

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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PACKAGE OPTION ADDENDUM

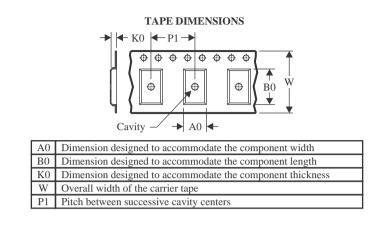
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| *All dimensions are nominal | |
|-----------------------------|--|
| | |
| | |

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| 74ACT11032DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |



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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|--|
| 74ACT11032DR | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 | |

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | Τ (μm) | B (mm) |
|---------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 74ACT11032N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| 74ACT11032N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| 74ACT11032N.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| 74ACT11032N.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| 74ACT11032NE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| 74ACT11032NE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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